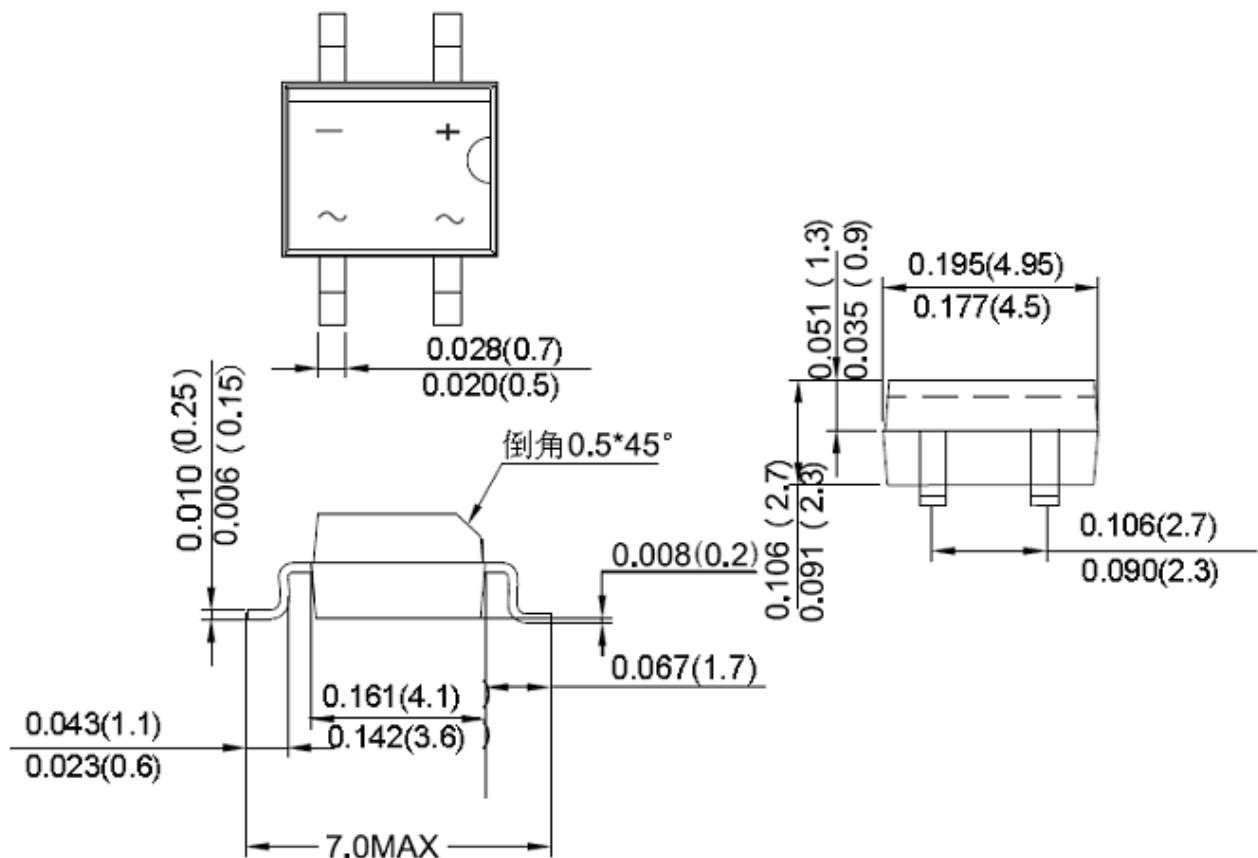


**MB05S THRU MB10S**
**Single-Phase 0.8A Surface Mount Glass Passivated Bridge Rectifier**
**Features:**

- Glass passivated die construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

**Mechanical Data:**

- Case: Reliable low cost construction utilizing molded plastic technique
- Terminals: Plated Leads Solderable per MILSTD-202,Method208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number

**Mechanical Dimensions: In Inches/mm**

**MBS**



## MB05S-MB10S

**Technical Data**  
**Data Sheet N0529, Rev. B**  
**Ordering Information:**

*Green Products*

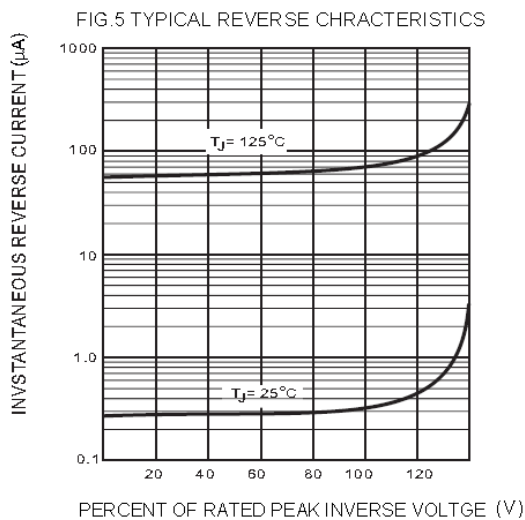
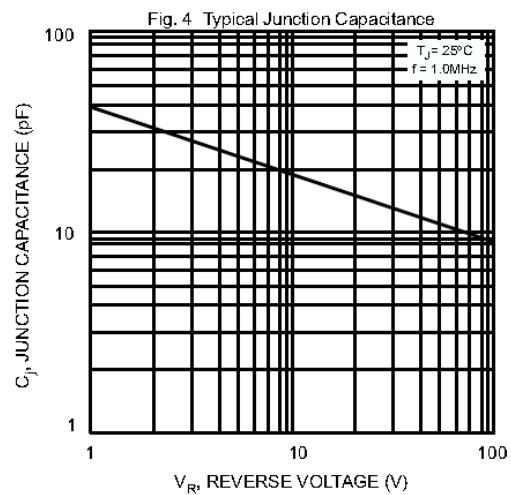
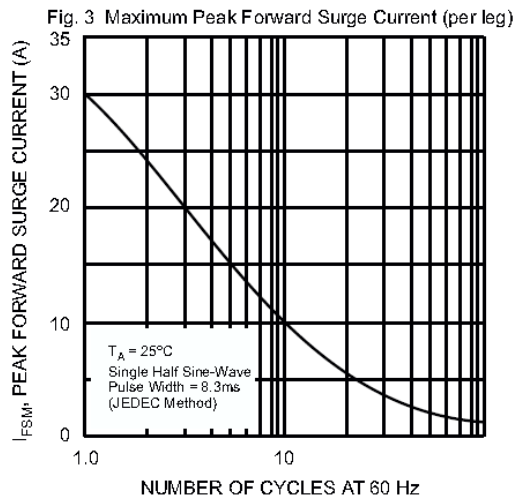
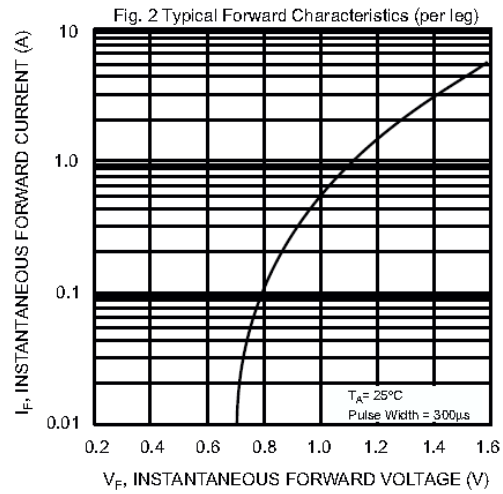
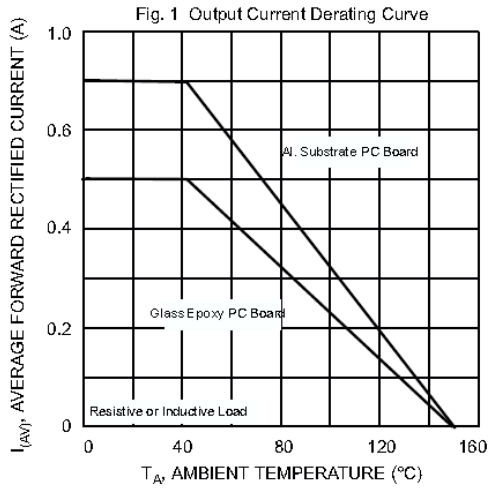
Device	Package	Shipping
MB05S-MB10S	MBS (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

### Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_{DC}$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Average forward rectified output current (Note 1) @ $T_A = 40^\circ\text{C}$ (Note 2) @ $T_A = 40^\circ\text{C}$	$I_O$	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30							A
Forward Voltage (per element) @ $I_F = 0.8\text{A}$	$V_{FM}$	1.1							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	$I_{RM}$	5 500							$\mu\text{A}$
Typical Junction Capacitance(per leg) (Note 3)	$C_J$	13							pF
Typical Thermal Resistance (per leg)	$R_{\theta JA}$ $R_{\theta JL}$	70 20							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.  
 2. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.  
 3. Measured at 1.0 MHz and applied reverse voltage of 4.0 VDC





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